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(US)(57) **ABSTRACT**(21) Appl. No.: **18/521,175**(22) Filed: **Nov. 28, 2023****Related U.S. Application Data**(60) Provisional application No. 63/477,274, filed on Dec.
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According to one or more embodiments of the disclosure, an apparatus comprising a pad above a semiconductor substrate, an n-well in the semiconductor substrate, and a floating p-well in the semiconductor substrate is provided. The floating p-well is below the pad and surrounded by the n-well in the semiconductor substrate.

